

### Features

- ◆ The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- ◆ For surface mounted applications
- ◆ Built-in strain relief, ideal for automated placement
- ◆ Low reverse leakage
- ◆ High forward surge current capability
- ◆ High temperature soldering guaranteed  
250°C/10 seconds at terminals

### Mechanical Data

**Case :** Molded plastic body

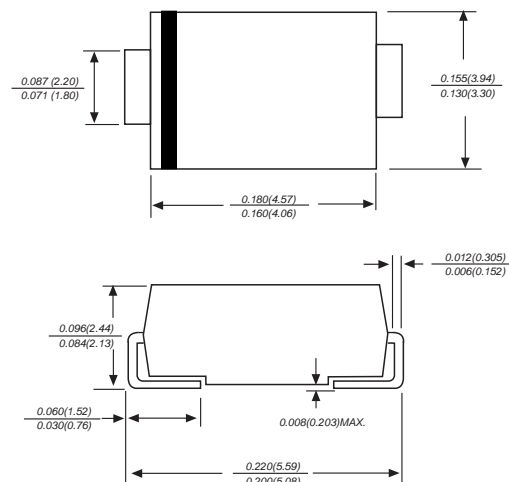
**Terminals :** Solder plated, solderable per MIL-STD-750, Method 2026

**Polarity :** Polarity symbol marking on body

**Mounting Position :** Any

**Weight :** 0.0035 ounce, 0.098 grams

DO-214AA/SMB



Dimensions in inches and (millimeters)

### Maximum Ratings And Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	SYMBOLS	SS54L	SS545L	SS55L	SS56L	SS58L	SS510L	UNITS
Maximum repetitive peak reverse voltage	$V_{RRM}$	40	45	50	60	80	100	V
Maximum RMS voltage	$V_{RMS}$	28	31.5	35	42	56	70	V
Maximum DC blocking voltage	$V_{DC}$	40	45	50	60	80	100	V
Maximum average forward rectified current at $T_L=100^\circ\text{C}$	$I_{(AV)}$	5.0						A
Peak forward surge current, 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	120.0						A
Maximum instantaneous forward voltage at 5.0A	$V_F$	0.48			0.55	0.70		V
Maximum DC reverse current at rated DC blocking voltage $T_A=25^\circ\text{C}$ $T_A=125^\circ\text{C}$	$I_R$	0.5 50				0.2 20		mA
Typical thermal resistance	$R_{\theta JA}$	85.0						$^\circ\text{C/W}$
Operating junction temperature range	$T_J$	-55 to +150						$^\circ\text{C}$
Storage temperature range	$T_{STG}$	-55 to +150						$^\circ\text{C}$

**Ratings And Characteristic Curves**

FIG. 1- DERATING CURVE OUTPUT RECTIFIED CURRENT

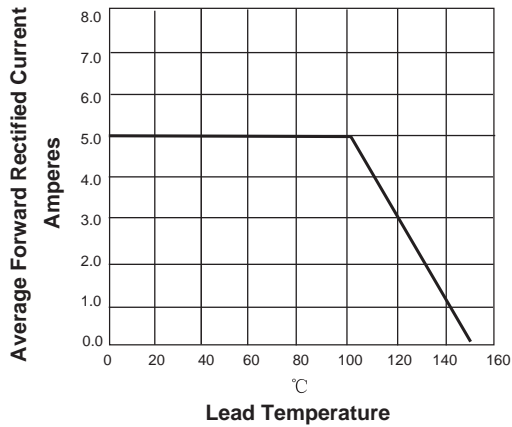


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT PER LEG

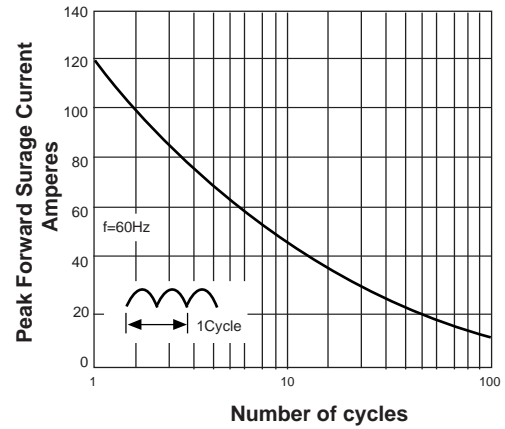


FIG. 3-TYPICAL FORWARD VOLTAGE CHARACTERISTICS

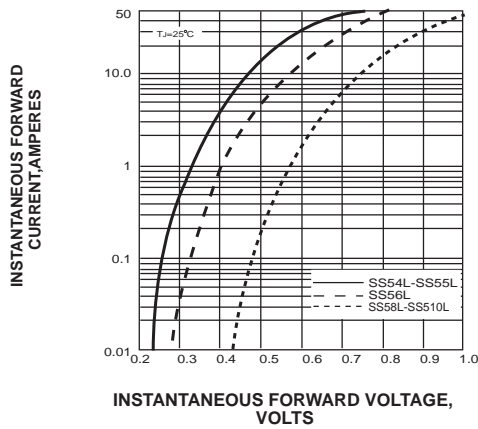
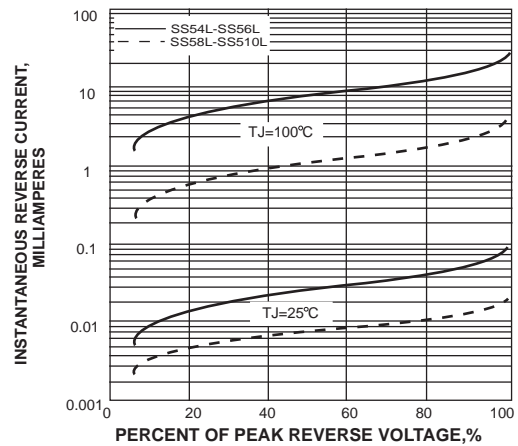
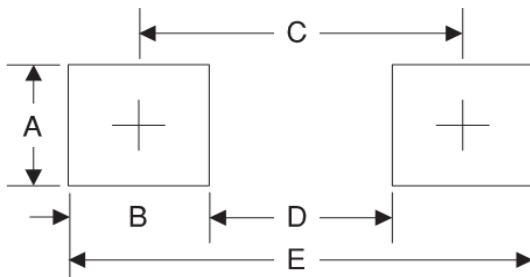


FIG. 4-TYPICAL REVERSE LEAKAGE CHARACTERISTICS

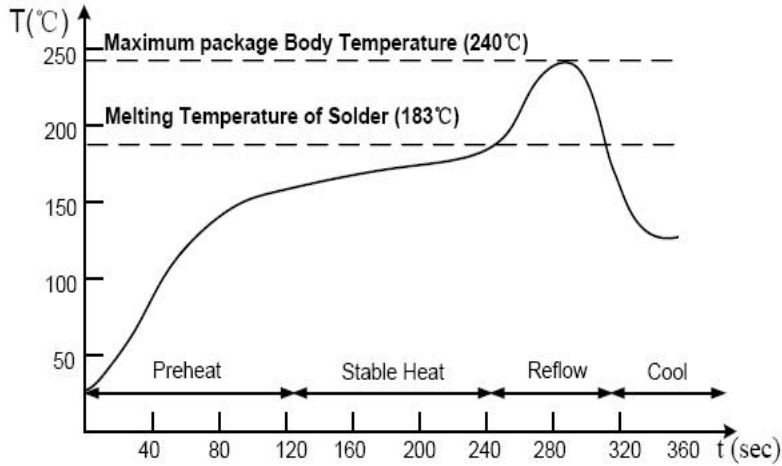


**Suggested Pad Layout**



Symbol	Unit (mm)	Unit (inch)
A	2.30	0.091
B	2.00	0.078
C	4.10	0.161
D	2.10	0.083
E	6.10	0.240

**Suggested Soldering Temperature Profile**

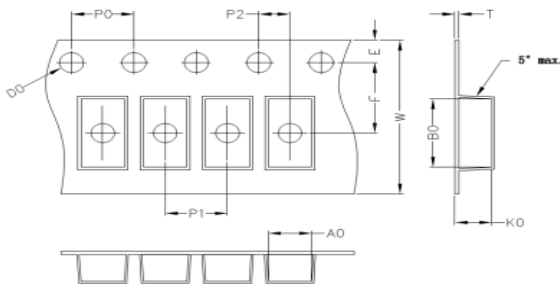


**Note**

- Recommended reflow methods: IR, vapor phase oven, hot air oven, wave solder.
- The device can be exposed to a maximum temperature of 265°C for 10 seconds.
- Devices can be cleaned using standard industry methods and solvents.
- If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

**Package Information**

**Carrier Dimension(mm)**



<b>A0</b>	<b>B0</b>	<b>K0</b>	<b>D0</b>	<b>E</b>	<b>F</b>
3.80	5.40	2.45	1.55	1.75	5.50
<b>P0</b>	<b>P1</b>	<b>P2</b>	<b>T</b>	<b>W</b>	<b>Tolerance</b>
4.0	8.0	2.0	0.25	12	0.1

**Package Specifications**

Package	Reel Size	Reel DIA. (mm)	Q'TY/Reel (Kpcs)	Box Size (mm)	QTY/Box (Kpcs)	Carton Size (mm)	Q'TY/Carton (Kpcs)
SMB	13'	330	3.0	340	6.0	360*360*360	48